

SYSTEM FOR IN SITU SEED LAYER REMEDIATION

ABSTRACT

The present invention provides a system for removing surface contaminants from a copper seed layer disposed upon a semiconductor substrate (210), in preparation for electrochemical deposition. An electrochemical deposition apparatus (202) is provided, having a contaminant remediation module (204) housed within. The semiconductor substrate (210) is transferred into the remediation module (204), where it is exposed in a reactive remediation system (216). Contaminants are removed from the surface of the copper seed layer, followed by an immediate transfer (212) of the substrate (210) from the remediation module (204) into a plating system (208) also housed within the electrochemical deposition apparatus (202).